

IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following new Abstract of the Disclosure:

ABSTRACT OF THE DISCLOSURE

A multilayer substrate includes an internal conductor connection structure having first and second via conductors adjacent to each other in the multilayer substrate and a first line conductor disposed in the multilayer substrate. The first via conductor includes a first continuous via conductor arranged to extend in a direction away from the second via conductor, and the first via conductor is connected to the first line conductor through the first continuous via conductor.